

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT5381000

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHUN-CHIA CHEN	02/13/2019
ZHEN-YEN LAI	02/13/2019
CHIH-WEI HSU	02/13/2019
TZU-DER CHUANG	02/13/2019
CHING-YEH CHEN	02/13/2019
RECEIVING PARTY DATA	
Name:	MEDIATEK INC.
Street Address:	NO. 1, DUSING ROAD 1
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSINCHU CITY
State/Country:	TAIWAN
Postal Code:	30078
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16248452
CORRESPONDENCE DATA	
Fax Number:	(206)792-5742
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	949-383-5384
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Correspondent Name:	HAN IP PLLC
Address Line 1:	500 UNION STREET
Address Line 2:	SUITE 800
Address Line 4:	SEATTLE, WASHINGTON 98101
ATTORNEY DOCKET NUMBER:	MDTK.0327US
NAME OF SUBMITTER:	ANDY M. HAN
SIGNATURE:	/Andy M. Han/
DATE SIGNED:	02/19/2019
This document serves as an Oath/Declaration (37 CFR 1.63).	

PATENT

Total Attachments: 4

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ASSIGNMENT

PARTIES TO THE ASSIGNMENT

Assignor(s):

- | | | |
|-------------------|-------------------|-------------------|
| 1. Chun-Chia Chen | 3. Chih-Wei Hsu | 5. Ching-Yeh Chen |
| 2. Zhen-Yen Lai | 4. Tzu-Der Chuang | |

Assignee:

MediaTek Inc.
No. 1, Dusing Road 1, Science-Based Industrial Park
Hsinchu City 30078, Taiwan, R.O.C.

WHEREAS, ASSIGNOR(S) (listed above) are inventor(s) of the above-identified invention for which:

provisional application(s) for United States Letters Patents was/were filed on

26 January 2018, 27 August 2018 and 03 October 2018 and was/were given U.S. Serial No(s). **62/622,234, 62/723,014 and 62/740,470, respectively**; and/or

a non-provisional application for United States Letters Patent was/is:

filed on **15 January 2019** and was given U.S. Serial No. **16/248,452**; or filed concurrently herewith.

Assignors hereby authorize and request ASSIGNEE's legal representatives, who are associated with customer number **13859**, to handle all matters related to the above-identified application.

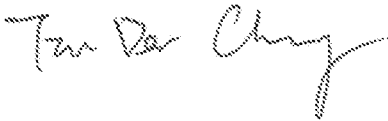
WHEREAS, MediaTek Inc. (hereinafter referred to as ASSIGNEE), a corporation of Taiwan, Republic of China (R.O.C.) having a place of business at No. 1, Dusing Road 1, Science-Based Industrial Park, Hsinchu City 30078, Taiwan, R.O.C., is desirous of acquiring the entire right, title and interest in and to the invention and in and to any letters patent that may be granted therefore in the United States and in any and all foreign countries;

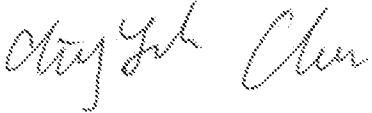
NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNORS hereby sell, assign and transfer unto ASSIGNEE, the entire right, title and interest in and to said invention, said application and any and all letters patent which may be granted for said invention in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisions, reissues and continuations thereof, including the right to file foreign applications directly in the name of ASSIGNEE and to claim priority rights deriving from said United States application to which said foreign applications are entitled by virtue of international convention, treaty or otherwise, said invention, application and all letters patent on said invention to be held and enjoyed by ASSIGNEE and its successors and assigns for their use and benefit and of their successors and assigns as fully and entirely as the same would have been held and enjoyed by ASSIGNORS had this assignment, transfer and sale not been made. ASSIGNORS hereby authorize and request the Commissioner of Patents and Trademarks to issue all letters patent on said invention to ASSIGNEE. ASSIGNORS agree to execute all instruments and documents required for the making and prosecution of applications for United States and foreign letters patent on said invention, for litigation regarding said letters patent, or for the purpose of protecting title to said invention or letters patent therefore.

Legal Name of First-Named Inventor: Chun-Chia CHEN	
Inventor's Signature: Chun-Chia Chen	Date: Feb. 13, 2019
Residence: Hsinchu City, Taiwan, R.O.C.	
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Inventor's Signature: Zhen-Yen Lai	Date: Feb 13, 2019
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Nationality: Taiwan, R.O.C.	
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Legal Name of Co-Inventor: Chih-Wei HSU	
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Legal Name of Co-Inventor: Tzu-Der CHUANG	
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Legal Name of Co-Inventor: Ching-Yeh CHEN	
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